

JNG75T120QS1

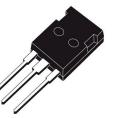
IGBT

Features

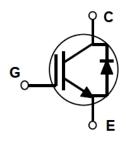
- 1200V,75A
- V_{CE(sat)(typ.)}= 1.9V@V_{GE}= 15V,I_C= 75A
- High speed switching
- Higher system efficiency
- Soft current turn-off waveforms

General Description

JIAEN Trench IGBTs offer lower losses and higher energy efficiency for application such as induction heating, UPS, AC & DC motor controls and general purpose inverter .



TO-247-3L Plus



Absolute Maximum Ratings

Symbol	Parameter	Value	Units
V _{CES}	Collector-Emitter Voltage	1200	V
Vges	Gate-Emitter Voltage	<u>+</u> 30	V
	Continuous Collector Current ($T_c=25$ °C)	115	A
lc	Continuous Collector Current (Tc=100°C)	75	A
Ісм	Pulsed Collector Current (Note 1)	230	A
lF	Diode Continuous Forward Current (Tc=100 °C)	75	А
Ifm	Diode Maximum Forward Current (Note 1)	250	А
t _{sc}	Short Circuit Withstand Time VGE=15V, Vcc≪960V, Tj≪150℃	10	us
D	Maximum Power Dissipation ($T_C=25$ °C)	625	W
PD	Maximum Power Dissipation (T _C =100°C)	250	W
TJ	Operating Junction Temperature Range	-40 to +150	°C
T _{STG}	Storage Temperature Range	-55 to +150	°C

Thermal Characteristics

Symbol	Parameter	Max.	Units
R _{th j-c}	Thermal Resistance, Junction to case for IGBT	0.2	°C/ W
Rth j-c	Thermal Resistance, Junction to case for Diode	0.4	°C/ W
R _{th j-a}	Thermal Resistance, Junction to Ambient	40	°C/ W



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Electrical Characteristics (Tc=25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
BV _{CES}	Collector-Emitter Breakdown Voltage	V _{GE} = 0V, I _C = 250uA	1200	-	-	V
I _{CES}	Collector-Emitter Leakage Current	V _{CE} = 1200V, V _{GE} = 0V	-	-	100	uA
	Gate Leakage Current, Forward	V_{GE} =30V, V_{CE} = 0V	-	-	100	nA
I _{GES}	Gate Leakage Current, Reverse	V_{GE} = -30V, V_{CE} = 0V	-	-	-100	nA
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE} = V_{CE}, I_C = 250 \text{uA}$	4.5	-	6.5	V
V _{CE(sat)}	Collector-Emitter Saturation Voltage	V _{GE} =15V, I _C = 75A	-	1.9	2.5	V
		V _{GE} =15V, I _C = 75A Tc = 125 ℃		2.3		
		V _{GE} =15V, I _C = 75A Tc = 150 ℃		2.6		
		V _{GE} =15V, I _C = 115A		2.2		
t d(on)	Turn-on Delay Time		-	205	-	ns
t r	Turn-on Rise Time	V _{cc} =600V	-	470	-	ns
t d(off)	Turn-off Delay Time	V _{GE} =15V	-	130	-	ns
t f	Turn-off Fall Time	Ic=75Α Rg=10Ω	-	295	-	ns
Eon	Turn-on Switching Loss	Inductive Load	-	19.1	-	mJ
Eoff	Turn-off Switching Loss	Tc=25 ℃	-	6	-	mJ
Ets	Total Switching Loss		-	25.1	-	mJ
t d(on)	Turn-on Delay Time		-	190	-	ns
tr	Turn-on Rise Time	V _{CC} =600V		365	-	ns
t d(off)	Turn-off Delay Time	V _{GE} =15V Ic =75A	-	170	-	ns
t f	Turn-off Fall Time	$R_G = 10\Omega$	-	345	-	ns
Eon	Turn-on Switching Loss	Inductive Load	-	15.7	-	mJ
Eoff	Turn-off Switching Loss	T _C =125 ℃	-	7.4	-	mJ
Ets	Total Switching Loss		-	23.1	-	mJ
Cies	Input Capacitance	V _{CE} =30V V _{GE} =0V f = 1MHz	-	7348	-	pF
Coes	Output Capacitance		-	312	-	pF
C _{res}	Reverse Transfer Capacitance		-	38	-	pF
Qg	Total Gate Charge	Vcc =600V V _{GE} =15V	-	270		nC
Qge	Gate-Emitter Charge		-	105		nC
Qgc	Gate-Collector Charge	I _C = 75A	-	140		nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature



Electrical Characteristics of Diode (Tc=25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V _F	Diode Forward Voltage	I _F = 75A	-	2.1	3.2	V
trr	Diode Reverse Recovery Time	V _{CE} = 400V	-	530		ns
lrr	Diode peak Reverse Recovery Current	I _F = 75A	-	8.5		А
Q _{r r}	Diode Reverse Recovery Charge	dIF/dt = 200A/us	-	1890		nC



Typical Performance Characteristics

Figure 1. Typical Output Characteristics

Tc=25 °C 300 -VGE=12V 250 VGE=15V VGE=17V -200 € 150 $\underline{\circ}$ 100 50 0 0 1 2 3 4 5 VCE (V)

Figure 2. Typical Saturation Voltage

Characteristics VG=15V

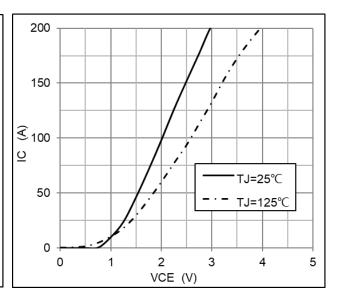


Figure 3. Saturation Voltage vs. Case Temperature at Variant Current Level

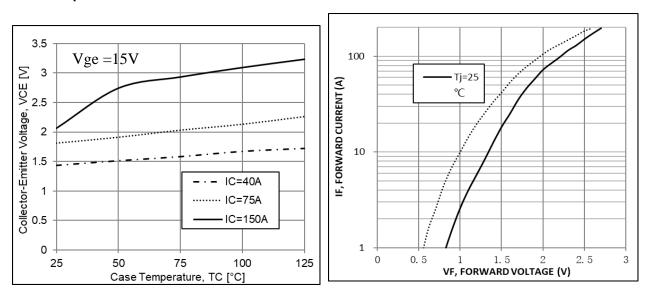


Figure 4. Forward Characteristics

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Figure 5. Saturation Voltage vs. VGE Tc=25C

Figure 6. Saturation Voltage vs. VGE Tc=125C

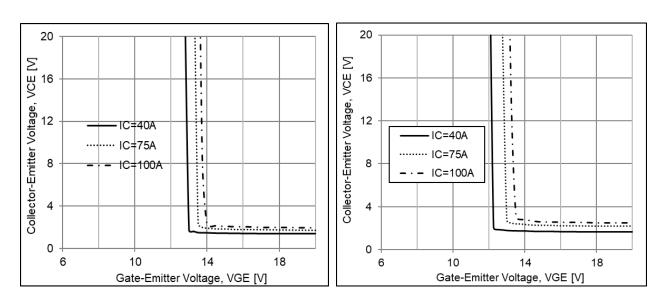


Figure 7.Switching Loss vs. Gate Resistance

(VCC=600V, VGE= \pm 15V, IC=75A,)

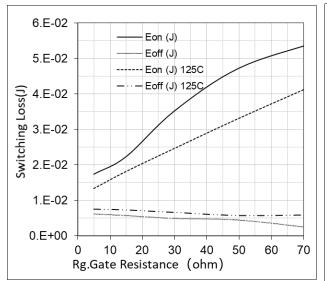
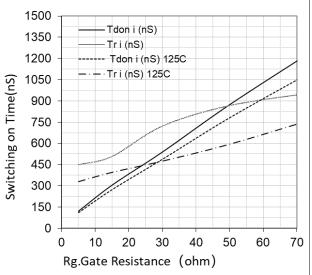


Figure 8. Turn-On Characteristics vs. Gate

Resistance (VCC=600V, VGE= \pm 15V, IC=75A)



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Figure 9. Turn-Off Characteristics vs. Gate

Resistance (VCC=600V, VGE=±15V, IC=75A)

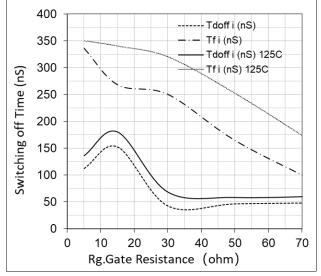


Figure 11. Turn-On Characteristics vs. Collector

Current (VGE=±15V, RG=5 OHM, VCC=600V)

50

40

Tdon i (nS) 125C

Tr i (nS) 125C

– Tri (nS)

----- Tdon i (nS)

Figure 10. Switching Loss vs. Collector Current

(VGE=±15V, RG= 10 ohm, VCC=600V)

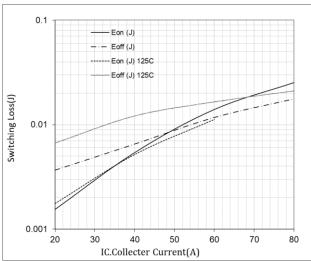
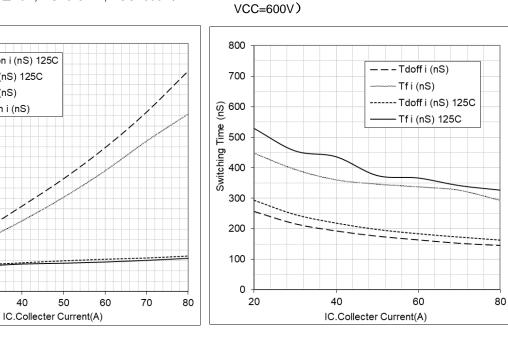


Figure 12. Turn-Off Characteristics vs. **Collector Current** (VGE= \pm 15V, RG=5 OHM,



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600

500

400

300

200

100

0

20

30

Switching Time (nS)



Figure 13. Gate Charge Characteristics

RL=10 ohm TC=25C ,Vcc=600, 400V 200V

Figure 14. Reverse Recovery Current

VCC=400V, RG=10 ohm, VG= \pm 15V IL=500uH

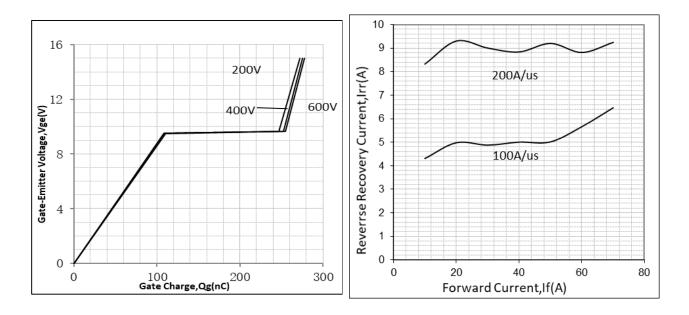


Figure 15. Stored Charge VCC=600V, RG= 10 ohm, VG=±15V IL=500uH

Figure 16. Reverse Recovery Time

VCC=400V, RG=10 ohm, VG= \pm 15V IL=500uH

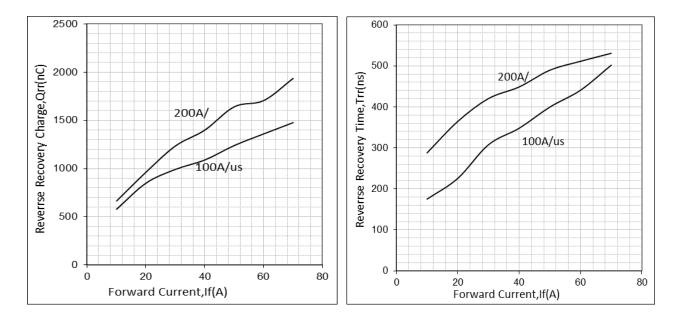




Figure 17. SOA Characteristics



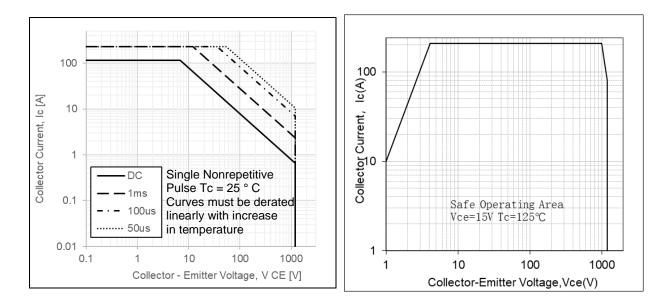
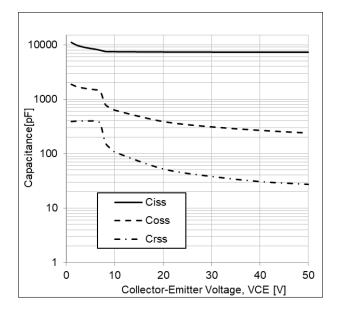


Figure 19. Capacitance Characteristics





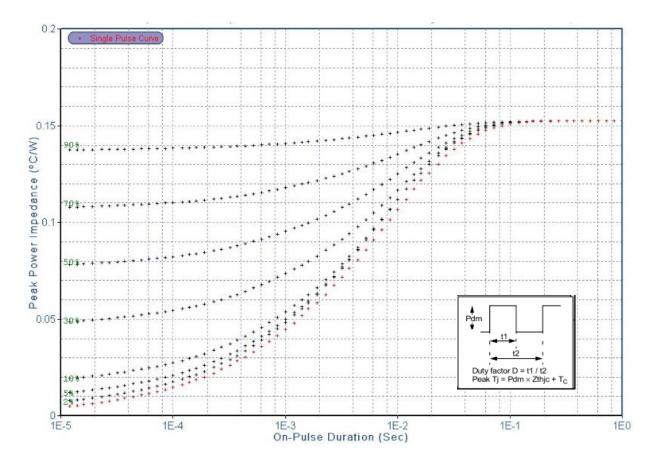
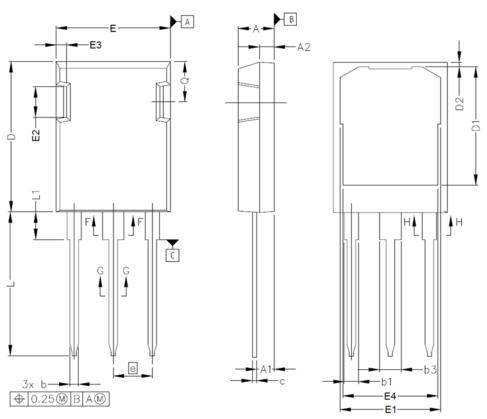


Figure 20. Transient Thermal Impedance of IGBT



Mechanical Diamensions



SYMBOL	MIN	MAX
А	4.83	5.21
A1	2.29	2.54
A2	1.91	2.16
b'	1.07	1.28
b	1.07	1.33
b1	1.91	2.41
b2	1.91	2.16
b3	2.87	3.38
b4	2.87	3.13
c'	0.55	0.65
с	0.55	0.68
D	20.80	21.10
D1	16.25	17.65
D2	0.50	0.80

SYMBOL	MIN	MAX		
Е	15.75	16.13		
E1	13.10 14.15			
E2	3.68 5.10			
E3	1.00	1.90		
E4	12.38	13.43		
e	5.44 BSC			
Ν	3			
L	19.81	20.32		
L1	3.70	4.00		
Q	5.49 6.00			



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